

AuSn(Gold-Tin) Solder
【S-type】

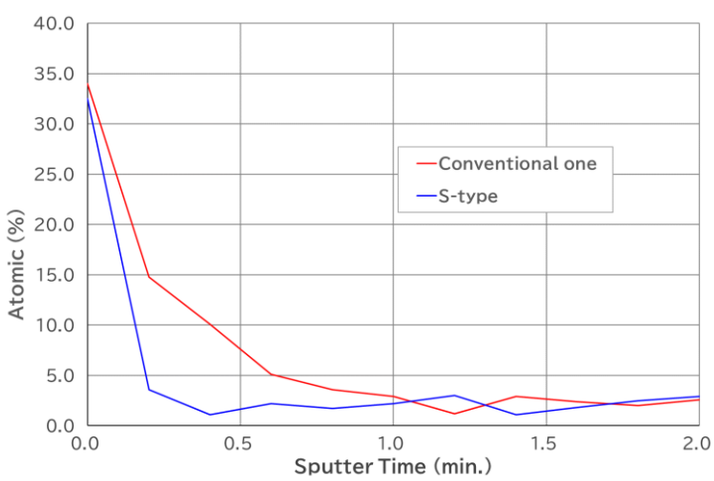
We can mold into various shapes such as frame shape, ribbon, ball, etc. according to your request.

Advantage

- ☑ Capable of molding into various shapes and performing ultra-fine processing.
- ☑ A thin oxide film through our unique manufacturing process.
- ☑ Exhibits excellent wettability even on thermally degraded substrates

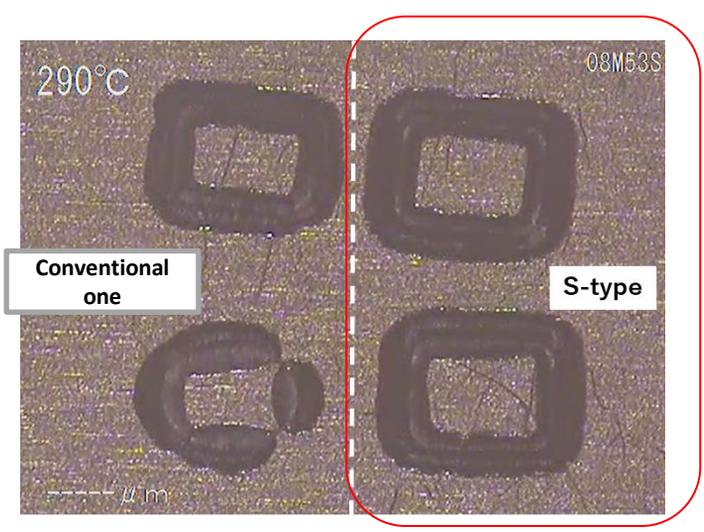
Comparison of surface oxide film thickness

▸ Auger electron spectroscopy(AES) Depth direction analysis <O excerpt>



Comparison of wettability

▸ Compares the melting of thermally degraded gold-plated substrates between the conventional product and S-type.



▸ **Thin surface oxidation film thickness achieves excellent wettability**

Reduction of surface oxidation film thickness by a different method from the conventional one.

The Characteristics of AuSn Solder

Composition	Au-20Sn	Au-22Sn
Melting point (solid line)	280	280
Melting point (liquid line)	280	315
Specific gravity	14.52	14.17
Hardness(Hb)	118	-

※ Our available composition

Applications

Sealing/solder materials for quartz oscillators, semiconductor lasers, communication devices



If you have any question about this product, please feel free to contact us.
https://crossmining.smm-g.com/

X-MINING
SUMITOMO METAL MINING